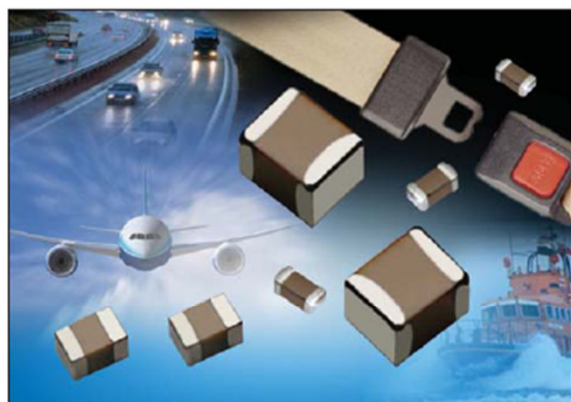




The FLEXITERM™ layer protects the component from any damage to the ceramic resulting from mechanical stress during PCB assembly or use with end customers. Board flexure type mechanical damage accounts for the majority of MLCC failures. The addition of the cascade structure protects the component from low insulation resistance failure resulting from other common causes for failure; thermal stress damage, repetitive strike ESD damage and placement damage. With the inclusion of the cascade design structure to complement the FLEXITERM™ layer, the FLEXISAFE range of capacitors has unbeatable safety features.

FS03

5

C

104

K

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A

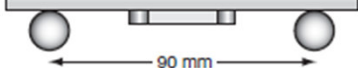
Special Code
A = Std. Product

[illegible]

X7R Dielectric

Specifications and Test Methods



Parameter/Test		X7R Specification Limits	Measuring Conditions	
Operating Temperature Range		-55°C to +125°C	Temperature Cycle Chamber	
Capacitance		Within specified tolerance	Freq.: 1.0 kHz $\pm$ 10% Voltage: 1.0Vrms $\pm$.2V For Cap > 10 μ F, 0.5Vrms @ 120Hz	
Dissipation Factor		$\leq$ 2.5% for $\geq$ 50V DC rating $\leq$ 3.0% for 25V DC rating $\leq$ 3.5% for 16V DC rating $\leq$ 5.0% for $\leq$ 10V DC rating		
Insulation Resistance		100,000M Ω or 1000M Ω - μ F, whichever is less	Charge device with rated voltage for 120 $\pm$ 5 secs @ room temp/humidity	
Dielectric Strength		No breakdown or visual defects	Charge device with 300% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max) Note: Charge device with 150% of rated voltage for 500V devices.	
Resistance to Flexure Stresses	Appearance	No defects	Deflection: 5 mm Test Time: 30 seconds 	
	Capacitance Variation	$\leq \pm 12\%$		
	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	$\geq$ Initial Value $\times$ 0.3		
Solderability		$\geq$ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at 230 $\pm$ 5°C for 5.0 $\pm$ 0.5 seconds	
Resistance to Solder Heat	Appearance	No defects, <25% leaching of either end terminal	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 $\pm$ 2 hours before measuring electrical properties.	
	Capacitance Variation	$\leq \pm 7.5\%$		
	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	Meets Initial Values (As Above)		
	Dielectric Strength	Meets Initial Values (As Above)		
Thermal Shock	Appearance	No visual defects	Step 1: -55°C $\pm$ 2°	30 $\pm$ 3 minutes
	Capacitance Variation	$\leq \pm 7.5\%$	Step 2: Room Temp	$\leq$ 3 minutes
	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C $\pm$ 2°	30 $\pm$ 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	$\leq$ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 $\pm$ 2 hours at room temperature	
Load Life	Appearance	No visual defects	Charge device with 1.5 rated voltage ($\leq$ 10V) in test chamber set at 125°C $\pm$ 2°C for 1000 hours (+48, -0) Remove from test chamber and stabilize at room temperature for 24 $\pm$ 2 hours before measuring.	
	Capacitance Variation	$\leq \pm 12.5\%$		
	Dissipation Factor	$\leq$ Initial Value $\times$ 2.0 (See Above)		
	Insulation Resistance	$\geq$ Initial Value $\times$ 0.3 (See Above)		
	Dielectric Strength	Meets Initial Values (As Above)		
Load Humidity	Appearance	No visual defects	Store in a test chamber set at 85°C $\pm$ 2°C/ 85% $\pm$ 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied. Remove from chamber and stabilize at room temperature and humidity for 24 $\pm$ 2 hours before measuring.	
	Capacitance Variation	$\leq \pm 12.5\%$		
	Dissipation Factor	$\leq$ Initial Value $\times$ 2.0 (See Above)		
	Insulation Resistance	$\geq$ Initial Value $\times$ 0.3 (See Above)		
	Dielectric Strength	Meets Initial Values (As Above)		

Packaging of Chip Components



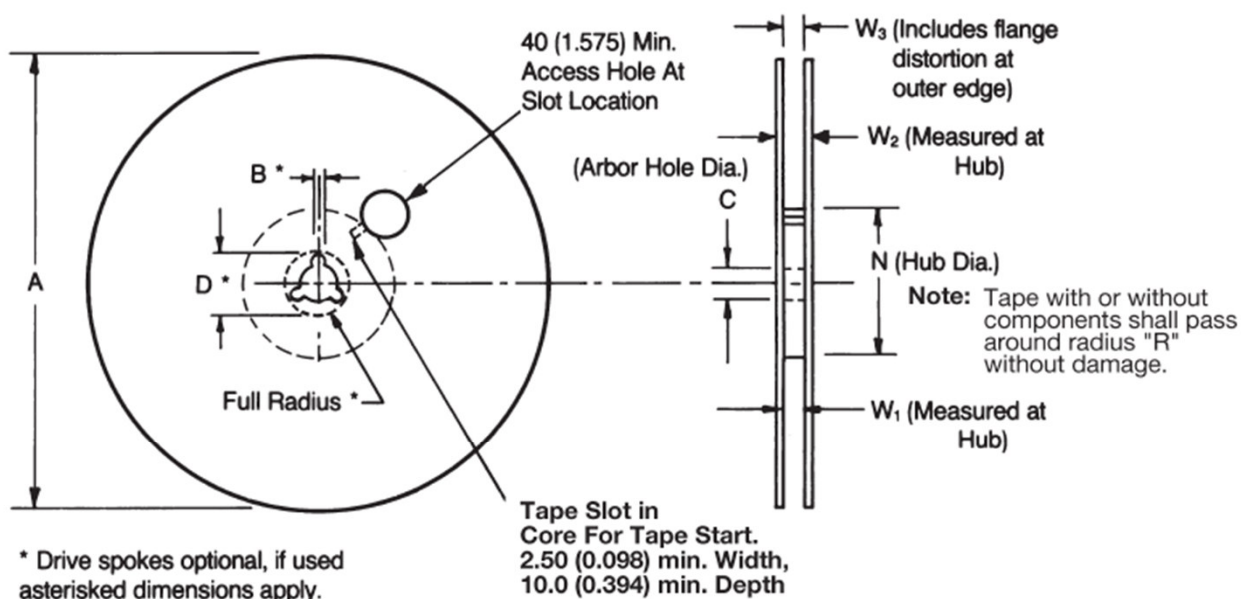
Automatic Insertion Packaging

TAPE & REEL QUANTITIES

All tape and reel specifications are in compliance with RS481.

	8mm	12mm
Paper or Embossed Carrier	0612, 0508, 0805, 1206, 1210	
Embossed Only		1808, 1812, 1825, 2220, 2225
Paper Only	0201, 0306, 0402, 0603	
Qty. per Reel/7" Reel	2,000, 3,000 or 4,000, 10,000, 15,000 Contact factory for exact quantity	3,000, 500, 1,000 Contact factory for exact quantity
Qty. per Reel/13" Reel	5,000, 10,000, 50,000 Contact factory for exact quantity	10,000, 4,000

REEL DIMENSIONS



Tape Size ⁽¹⁾	A Max.	B* Min.	C	D* Min.	N Min.	W ₁	W ₂ Max.	W ₃
8mm						8.40 ± 0.15 (0.331 ± 0.006)	14.4 (0.567)	7.90 Min. (0.311) 10.9 Max. (0.429)
12mm	330 (12.992)	1.5 (0.059)	13.0 ± 0.50 (0.512 ± 0.008)	20.2 (0.795)	50.0 (1.969)	12.4 ± 0.20 (0.488 ± 0.007)	18.4 (0.724)	11.9 Min. (0.469) 15.4 Max. (0.607)

Metric dimensions will govern.

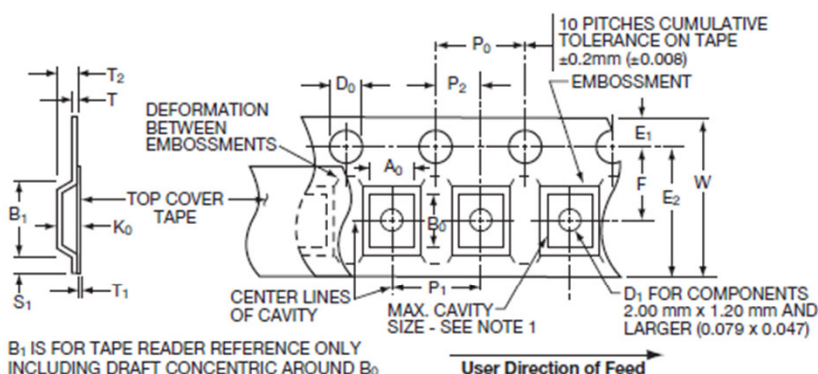
English measurements rounded and for reference only.

(1) For tape sizes 16mm and 24mm (used with chip size 3640) consult EIA RS-481 latest revision.

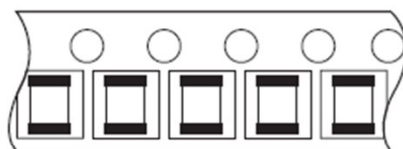
Embossed Carrier Configuration



8 & 12mm Tape Only



Chip Orientation



8 & 12mm Embossed Tape Metric Dimensions Will Govern

CONSTANT DIMENSIONS

Tape Size	D ₀	E	P ₀	P ₂	S ₁ Min.	T Max.	T ₁
8mm and 12mm	1.50 ^{+0.10} _{-0.05} (0.059 ^{+0.004} _{-0.002})	1.75 ± 0.10 (0.069 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)	2.0 ± 0.05 (0.079 ± 0.002)	0.60 (0.024)	0.60 (0.024)	0.10 (0.004) Max.

VARIABLE DIMENSIONS

Tape Size	B ₁ Max.	D ₁ Min.	E ₂ Min.	F	P ₁ See Note 5	R Min. See Note 2	T ₂	W Max.	A ₀ B ₀ K ₀
8mm	4.35 (0.171)	1.00 (0.039)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	4.00 ± 0.10 (0.157 ± 0.004)	25.0 (0.984)	2.50 Max. (0.098)	8.30 (0.327)	See Note 1
12mm	8.20 (0.323)	1.50 (0.059)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	4.00 ± 0.10 (0.157 ± 0.004)	30.0 (1.181)	6.50 Max. (0.256)	12.3 (0.484)	See Note 1
8mm 1/2 Pitch	4.35 (0.171)	1.00 (0.039)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	2.00 ± 0.10 (0.079 ± 0.004)	25.0 (0.984)	2.50 Max. (0.098)	8.30 (0.327)	See Note 1
12mm Double Pitch	8.20 (0.323)	1.50 (0.059)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	8.00 ± 0.10 (0.315 ± 0.004)	30.0 (1.181)	6.50 Max. (0.256)	12.3 (0.484)	See Note 1

NOTES:

1. The cavity defined by A₀, B₀, and K₀ shall be configured to provide the following:

Surround the component with sufficient clearance such that:

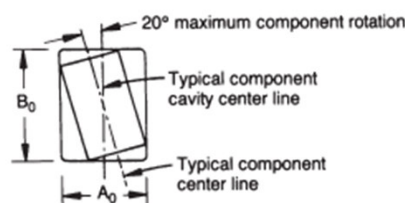
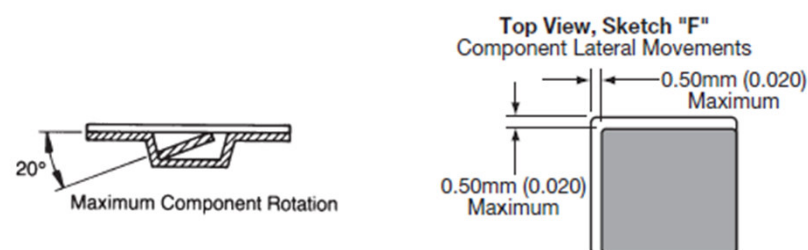
- the component does not protrude beyond the sealing plane of the cover tape.
- the component can be removed from the cavity in a vertical direction without mechanical restriction, after the cover tape has been removed.
- rotation of the component is limited to 20° maximum (see Sketches D & E).
- lateral movement of the component is restricted to 0.5mm maximum (see Sketch F).

2. Tape with or without components shall pass around radius "R" without damage.

3. Bar code labeling (if required) shall be on the side of the reel opposite the round sprocket holes. Refer to EIA-556.

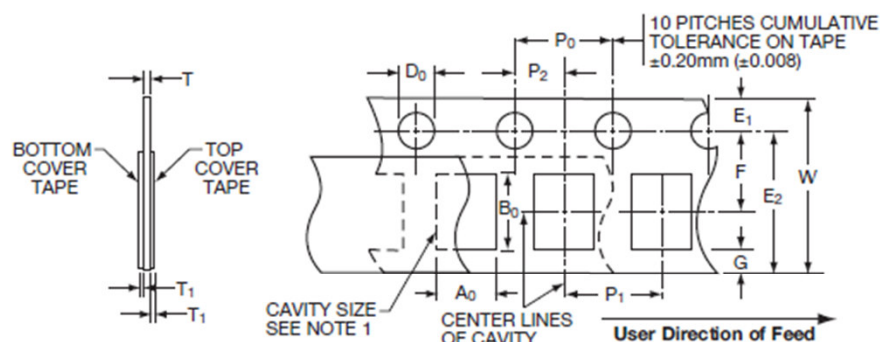
4. B₁ dimension is a reference dimension for tape feeder clearance only.

5. If P₁ = 2.0mm, the tape may not properly index in all tape feeders.



Paper Carrier Configuration

8 & 12mm Tape Only



8 & 12mm Paper Tape Metric Dimensions Will Govern

CONSTANT DIMENSIONS

Tape Size	D ₀	E	P ₀	P ₂	T ₁	G. Min.	R Min.
8mm and 12mm	1.50 ± 0.10 (0.059 ± 0.004)	1.75 ± 0.10 (0.069 ± 0.004)	4.00 ± 0.10 (0.157 ± 0.004)	2.00 ± 0.05 (0.079 ± 0.002)	0.10 (0.004) Max.	0.75 (0.030) Min.	25.0 (0.984) See Note 2 Min.

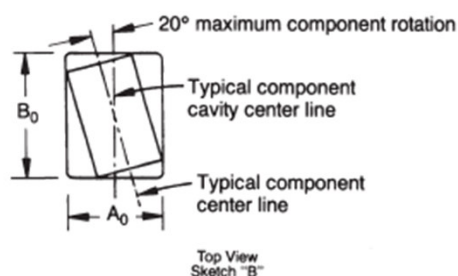
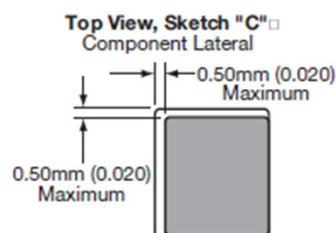
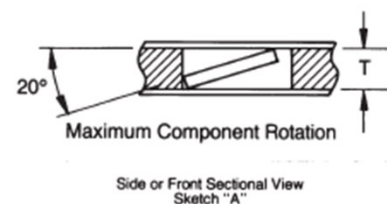
VARIABLE DIMENSIONS

Tape Size	P ₁ See Note 4	E ₂ Min.	F	W	A ₀ B ₀	T
8mm	4.00 ± 0.10 (0.157 ± 0.004)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	8.00 ± 0.30 (0.315 ± 0.012)	See Note 1	1.10mm (0.043) Max. for Paper Base Tape and 1.60mm (0.063) Max. for Non-Paper Base Compositions
12mm	4.00 ± 0.10 (0.157 ± 0.004)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	12.0 ± 0.30 (0.472 ± 0.012)		
8mm 1/2 Pitch	2.00 ± 0.05 (0.079 ± 0.002)	6.25 (0.246)	3.50 ± 0.05 (0.138 ± 0.002)	8.00 ± 0.30 (0.315 ± 0.012)		
12mm Double Pitch	8.00 ± 0.10 (0.315 ± 0.004)	10.25 (0.404)	5.50 ± 0.05 (0.217 ± 0.002)	12.0 ± 0.30 (0.472 ± 0.012)		

NOTES:

- The cavity defined by A₀, B₀, and T shall be configured to provide sufficient clearance surrounding the component so that:
 - the component does not protrude beyond either surface of the carrier tape;
 - the component can be removed from the cavity in a vertical direction without mechanical restriction after the top cover tape has been removed;
 - rotation of the component is limited to 20° maximum (see Sketches A & B);
 - lateral movement of the component is restricted to 0.5mm maximum (see Sketch C).

- Tape with or without components shall pass around radius "R" without damage.
- Bar code labeling (if required) shall be on the side of the reel opposite the sprocket holes. Refer to EIA-556.
- If P₁ = 2.0mm, the tape may not properly index in all tape feeders.



Bar Code Labeling Standard

AVX bar code labeling is available and follows latest version of EIA-556

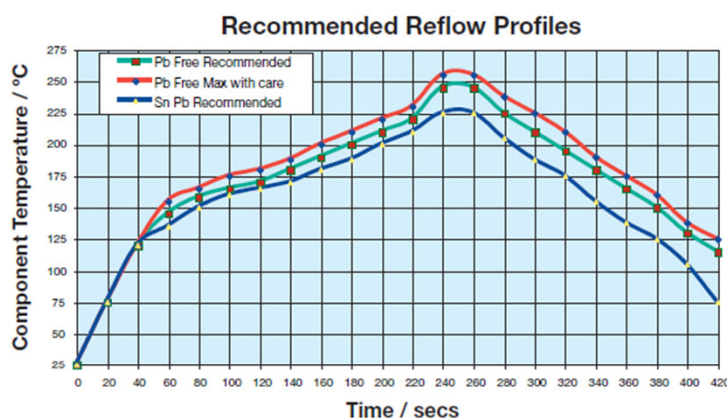
Surface Mounting Guide



Recommended Soldering Profiles

REFLOW SOLDER PROFILES

AVX RoHS compliant products utilize termination finishes (e.g. Sn or SnAg) that are compatible with all Pb-Free soldering systems and are fully reverse compatible with SnPb soldering systems. A recommended SnPb profile is shown for comparison; for Pb-Free soldering, IPC/JEDECJ-STD-020C may be referenced. The upper line in the chart shows the maximum envelope to which products are qualified (typically 3x reflow cycles at 260°C max). The center line gives the recommended profile for optimum wettability and soldering in Pb-Free Systems.



Preheat:

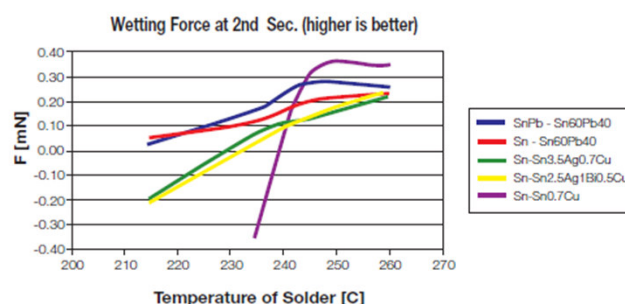
The pre-heat stabilizes the part and reduces the temperature differential prior to reflow. The initial ramp to 125°C may be rapid, but from that point (2-3)°C/sec is recommended to allow ceramic parts to heat uniformly and plastic encapsulated parts to stabilize through the glass transition temperature of the body (~ 180°C).

Reflow:

In the reflow phase, the maximum recommended time > 230°C is 40secs. Time at peak reflow is 10secs max.; optimum reflow is achieved at 250°C, (see wetting balance chart opposite) but products are qualified to 260°C max. Please reference individual product datasheets for maximum limits

Cool Down:

Cool down should not be forced and 6°C/sec is recommended. A slow cool down will result in a finer grain structure of the reflow solder in the solder fillet.



IMPORTANT NOTE: Typical Pb-Free reflow solders have a more dull and grainy appearance compared to traditional SnPb. Elevating the reflow temperature will not change this, but extending the cool down can help improve the visual appearance of the joint.

Solderability

Terminations to be well soldered after immersion in a 60/40 tin/lead solder bath at $235 \pm 5^\circ\text{C}$ for 2 ± 1 seconds.

Leaching

Terminations will resist leaching for at least the immersion times and conditions shown below.

Termination Type	Solder Tin/Lead/Silver	Solder Temp. °C	Immersion Time Seconds
Nickel Barrier	60/40/0	260 ± 5	30 ± 1

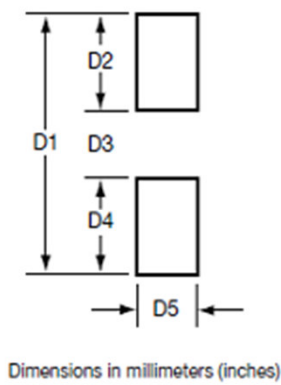
Surface Mounting Guide



MLC Chip Capacitors

REFLOW SOLDERING

Case Size	D1	D2	D3	D4	D5
0201	0.85 (0.033)	0.30 (0.012)	0.25 (0.010)	0.30 (0.014)	0.35 (0.014)
0402	1.70 (0.067)	0.60 (0.024)	0.50 (0.020)	0.60 (0.024)	0.50 (0.020)
0603	2.30 (0.091)	0.80 (0.031)	0.70 (0.028)	0.80 (0.031)	0.75 (0.030)
0805	3.00 (0.118)	1.00 (0.039)	1.00 (0.039)	1.00 (0.039)	1.25 (0.049)
1206	4.00 (0.157)	1.00 (0.039)	2.00 (0.079)	1.00 (0.039)	1.60 (0.063)
1210	4.00 (0.157)	1.00 (0.039)	2.00 (0.079)	1.00 (0.039)	2.50 (0.098)
1808	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	2.00 (0.079)
1812	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	3.00 (0.118)
1825	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	6.35 (0.250)
2220	6.60 (0.260)	1.00 (0.039)	4.60 (0.181)	1.00 (0.039)	5.00 (0.197)
2225	6.60 (0.260)	1.00 (0.039)	4.60 (0.181)	1.00 (0.039)	6.35 (0.250)



Component Pad Design

Component pads should be designed to achieve good solder fillets and minimize component movement during reflow soldering. Pad designs are given below for the most common sizes of multilayer ceramic capacitors for both wave and reflow soldering. The basis of these designs is:

- Pad width equal to component width. It is permissible to decrease this to as low as 85% of component width but it is not advisable to go below this.
- Pad overlap 0.5mm beneath component.
- Pad extension 0.5mm beyond components for reflow and 1.0mm for wave soldering.

Termination Cross-section

X7R Nickel Electrode FLEXITERM™

